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IN THE CLAIMS:

- 1. (Original) A substrate comprising
- a metal plate, and
- an insulating film, which is provided on the surface of the metal plate and which includes needle alumina particles and granular particles.
- 2. (Original) The substrate of claim 1, wherein the granular particles include at least one of silica particles, MgO particles, and TiO₂ particles.
- 3. (Original) The substrate of claim 2, wherein the granular particles include silica particles.
- 4. (Previously Presented) The substrate of claim 1, wherein the needle alumina particles have an aspect ratio of 6 to 15.
- 5. (Original) The substrate of claim 4, wherein the needle alumina particles have a major-axis length of 70 nm to 300 nm.
- 6. (Previously Presented) The substrate of claim 1, wherein the granular particles have a mean particle size of 5 nm to 80 nm.
- 7. (Previously Presented) The substrate of claim 1, wherein the insulating film includes 0.3 mass% to 80 mass% of the needle alumina particles.
- 8. (Previously Presented) The substrate of claim 1, wherein the insulating film has a thickness of 0.3 μm to 3.5 μm .
- 9. (Previously Presented) The substrate of claim 1, wherein the insulating film has a surface roughness of 0.3 μ m or less.
- 10. (Previously Presented) The substrate of claim 1, wherein the metal plate is made of Cu. an Fe-Ni-Cr alloy, an Fe-Cr alloy, an Fe-Ni alloy, Fe or Al.

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- 11. (Previously Presented) The substrate of claim 1, wherein the metal plate has a thickness of 0.05 mm to 0.5 mm.
 - 12. (Previously Presented) A wiring board comprising the substrate of claim 1, and
- a wiring pattern that has been formed on the surface of the insulating film on the substrate.

13-21. (Canceled)